

ABSTRACT OF THE DISCLOSURE

Die pads are provided which reduce moisture retention and thermal mismatch by employing a number of die pad sections or a die pad support portion with a number of relief regions. In each case, the die pad area to die area ratio is reduced to improve the thermal mismatch between the die and the die pad. Also, the die pad sections or relief regions are arranged in a spaced apart fashion to provide moisture escape paths between the die and the die pad.